

REMARKS

Applicants hereby provide a clean version of the paragraph amended in Applicants' November 26, 2002 Amendment. It should be noted that in that amendment, Applicants only corrected the spelling of "benzotriazole" in the first instance appearing in line 18 on page 6. Applicants, however, are hereby correcting both instances of "benzotriazole" appearing in line 18, on page 6.

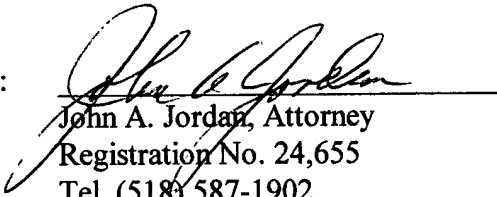
Accordingly Applicants are also attaching a page captioned **"VERSION WITH MARKINGS TO SHOW CHANGES MADE"**.

Applicants believe that Applicants' amendments are now fully compliant and, accordingly, in view of Applicants' amendments respectfully request the Examiner to reconsider and withdraw the outstanding rejection, allow the claims as presented and pass the case to issue.

Respectfully submitted,

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“VERSION WITH MARKINGS TO SHOW CHANGES MADE”.

Paragraph beginning at line 9 of page 6, has been amended as follows:

-- The dielectric layers of first circuitized substrate 1 and second circuitized substrate 15 are comprised of at least one layer of a material such as polyimide, polytetrafluoroethylene, or known epoxy-glass. The preferred material is polyimide. The substrates 1 and 15 can be combinations of these materials and can be flexible depending on the thickness and amounts of conductive layers 7 and 21 and conductors 11 and 25. Conductive layers 7 and 21 and conductors 11 and 25 are comprised of a metallic material such as copper, nickel, gold, chromium, solder, alloys of solder or combinations of these metals. Conductive layers 7 and 21 and conductors 11 and 25 can also have a protective layer (not shown) thereon, to protect the metallic material during storage. When conductive layers 7 and 21 are comprised of copper, the protective layer is usually a layer of benzotriazole ~~benzatriazole~~, chlorite, or immersion tin. Benzotriazole ~~Benzatrizaole~~ is an organic compound which binds to the copper protecting it from oxidation under high humidity and temperature conditions. Immersion tin is a very thin layer (about 30 microinches) of tin which displaces a small amount of copper on the surface of the conductive layer. Chlorite is a copper oxide adhesion promoter which is formed by contacting the copper surface of the conductive layers with a hot caustic solution (sodium or potassium hydroxide). FIG. 2 also illustrates that conductive apertures 9 and 23 are aligned such that the inner walls, when taken together, form substantially a single continuous aperture through both substrates. This continuous aperture forms a conductive wall for the subsequent formation of a solder member which will be explained in more detail later.--